A METHOD OF MANUFACTURING A SEMICONDUCTOR DEVICE

ABSTRACT OF THE DISCLOSURE

In a method of manufacturing a semiconductor device, there is provided, after the step of forming a plurality of chip forming regions having circuits on the front surface of a semiconductor wafer, and before the step of forming bump electrodes on the respective chip forming regions, the step of forming identifying marks respectively in the regions on the rear surface side of the semiconductor wafer which regions correspond to the respective chip forming regions.

Figure 5

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